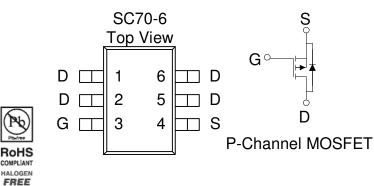


P-Channel 20-V (D-S) MOSFET

These miniature surface mount MOSFETs utilize a high cell density trench process to provide low $r_{DS(on)}$ and to ensure minimal power loss and heat dissipation. Typical applications are DC-DC converters and power management in portable and battery-powered products such as computers, printers, PCMCIA cards, cellular and cordless telephones.

- Low r_{DS(on)} provides higher efficiency and extends battery life
- Low thermal impedance copper leadframe SC70-6 saves board space
- Fast switching speed
- High performance trench technology

PRODUCT SUMMARY			
V _{DS} (V)	r _{DS(on)} (OHM)	I _D (A)	
	$0.079 @ V_{GS} = -4.5V$	-3.7	
-20	$0.110 @ V_{GS} = -2.5V$	-3.1	
	$0.160 @ V_{GS} = -1.8V$	-2.6	



ABSOLUTE MAXIMUM RATINGS ($T_A = 25$ °C UNLESS OTHERWISE NOTED)					
Parameter			Maximum	Units	
Drain-Source Voltage		V _{DS}	-20	V	
Gate-Source Voltage		V _{GS}	±8	v	
Continuous Drain Current ^a	$T_A=25^{\circ}C$	T	-3.7		
	$T_A=25^{\circ}C$ $T_A=70^{\circ}C$	ъD	-3.0	А	
Pulsed Drain Current ^b		IDM	-10		
Continuous Source Current (Diode Conduction) ^a		Is	±1.4	Α	
	T _A =25°C	D	1.56	W	
Power Dissipation ^a	T _A =25°C T _A =70°C	гD	0.81	,,	
Operating Junction and Storage Temperature Range		TJ, Tstg	-55 to 150	°C	

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Maximum	Units		
	$t \ll 5 \sec$	D	80	0000		
Maximum Junction-to-Ambient ^a	Steady-State	R _{THJA}	125	Ow.		

Notes

a. Surface Mounted on 1" x 1" FR4 Board.

b. Pulse width limited by maximum junction temperature

MS14P21



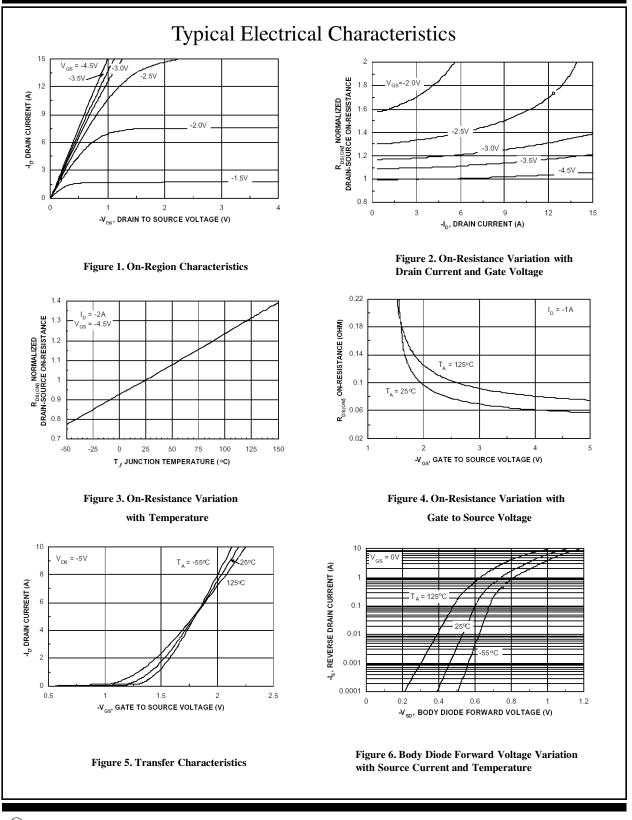
Parameter	Symbol	Test Conditions	Limits			Unit	
r ar anneter	Symbol	Test Conditions					
Static							
	GS(th)	$V_{DS} = V_{GS}, I_D = -250 \text{ uA}$	-0.4			V	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 8 V$			±100	nA	
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = -16 V, V_{GS} = 0 V$			-1	uA	
		$V_{DS} = -16 \text{ V}, V_{GS} = 0 \text{ V}, T_J = 55^{\circ}\text{C}$			-10		
On-State Drain Current ^A	I _{D(on)}	$V_{DS} = -5 V, V_{GS} = -4.5 V$	-5			Α	
		$V_{GS} = -4.5 \text{ V}, I_D = -3.7 \text{ A}$			79	mΩ	
Drain-Source On-Resistance ^A	r _{DS(on)}	$V_{GS} = -2.5 \text{ V}, I_D = -3.1 \text{ A}$			110		
		$V_{GS} = -1.8 \text{ V}, I_D = -2.6 \text{ A}$			160		
Forward Tranconductance ^A	\mathbf{g}_{fs}	$V_{DS} = -5 \text{ V}, \text{ I}_{D} = -1.25 \text{ A}$		9		S	
Diode Forward Voltage	V _{SD}	$I_{S} = -0.46 \text{ A}, V_{GS} = 0 \text{ V}$		-0.65		V	
Dynamic ^b							
Total Gate Charge	Q_{g}	$V_{DS} = -10 \text{ V}, V_{GS} = -4.5 \text{ V},$		7.2		nC	
Gate-Source Charge	Q _{gs}	$v_{\rm DS} = -10 v, v_{\rm GS} = -4.3 v,$ $I_{\rm D} = -3.7 {\rm A}$		1.7			
Gate-Drain Charge	Q_{gd}	$I_{\rm D} = -3.7$ A		1.5			
Turn-On Delay Time	t _{d(on)}			10			
Rise Time	t _r	$V_{DD} = -10 \text{ V}, \text{ I}_{L} = -1 \text{ A},$		9		ns	
Turn-Off Delay Time	t _{d(off)}	V_{GEN} = -4.5 V, R_G = 6 Ω		27			
Fall-Time	t _f			11			

Notes

- a. Pulse test: PW <= 300us duty cycle <= 2%.
- b. Guaranteed by design, not subject to production testing.
- c. Repetitive rating, pulse width limited by junction temperature.



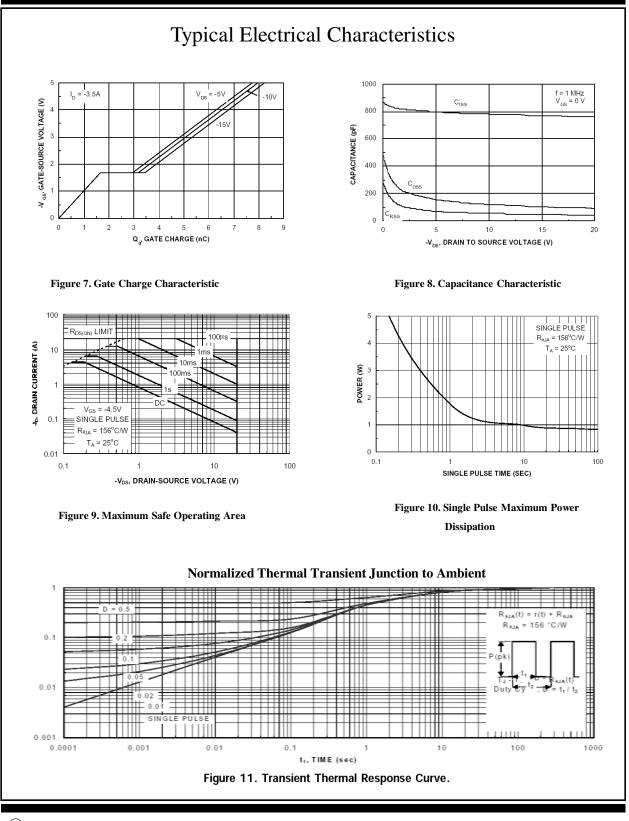
MS14P21



© PRELIMINARY



MS14P21



Publication Order Number: D



MS14P21

